

ABSTRACT

The present disclosure provides an electrostatic chuck and a base. The electrostatic chuck includes a chuck body, a voltage feed member, and a plurality of absorption members. The plurality of absorption members are arranged at the chuck body at intervals. Each absorption member includes an insulation layer, an electrode layer, and a dielectric layer arranged sequentially in a direction away from the chuck body. The voltage feed member is arranged between the absorption member and the chuck body and electrically contacts the electrode layers of the plurality of absorption members. The voltage feed member is configured to feed the DC voltage to the electrode layer of each absorption member. The plurality of wafers can be absorbed by the plurality of absorption members in a one-to-one correspondence. With the electrostatic chuck and the base of the present disclosure, the manufacturing difficulty and cost of the multi-wafer electrostatic chuck can be reduced, and the RF coupling efficiency and the semiconductor processing efficiency can be improved.